



AUTOMATED CHEMICAL SOLUTIONS

Chemicals and Controllers for PWB Fabrication

Product Overview

OXYshield AT-2323

Copper Anti-tarnish

Product Description

OXYshield AT-2323 is a concentrated anti-tarnish designed to preserve cleaned copper surfaces and prevent re-oxidation prior to subsequent processing. OXYshield AT-2323 deposits a uniform triazole film that promotes excellent dry film adhesion.

Physical Properties

Specific gravity:	1.03
pH:	6-8
Appearance:	clear, light amber liquid
Flash point:	> 200 °F

Operating Parameters

Concentration:	0.3 – 3.0% v/v, 0.5% nominal
Temperature:	70 – 100 °F

Storage

Store in original containers above 40 °F.

Safety

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

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